In the Claims:

Please cancel claims 11-14 and 15-16. Please amend claims 17-20. Please add new claims 34-42. The claims are as follows:

1. (Original) A method of forming a security enclosure, comprising:

providing an electronic assembly;

enclosing the assembly in a tamper respondent wrap, such that the wrap forms fold lines at a first and second end of the assembly;

placing the enclosed assembly in a fixture, wherein the fixture comprises a base upon which the assembly rests, a first stationary arm mounted on the base holding the fold lines at the first end of the assembly, a second arm slidably mounted on the base, and a traversing mechanism to bias the second arm toward the fold lines at the second end of the assembly; and

heating the enclosed assembly.

2. (Canceled)

3. (Previously presented) The method of claim 1, further comprising heating the enclosed assembly at a temperature of 40-90 °C.

4. (Previously presented) The method of claim 1, further comprising heating the enclosed assembly for 1 hour.

5. (Original) The method of claim 1, wherein the fixture comprises a clamping device.

6. (Original) The method of claim 1, wherein the tamper respondent wrap comprises a flexible material having tamper respondent detection devices.

7. (Original) The method of claim 1, wherein the tamper respondent wrap comprises:

at least one pierce and laser respondent layer;

a delamination respondent layer; and

an adhesive between the pierce and laser respondent layer and the delamination respondent layer.

8. (Original) The method of claim 7, wherein the pierce and laser respondent layer and the delamination respondent layer comprise a plurality of ink lines on at least one side of the pierce and laser respondent layer and the delamination respondent layer.

9. (Original) The method of claim 1, wherein the electronic assembly comprises a cryptographic processor.

10. (Original) The method of claim 9, wherein the cryptographic processor comprises a printed circuit board, having mounted thereon:

an encryption module to carry secured sensitive information;

a memory to store a key necessary to access the information;

an erase circuit to erase the information in the encryption module in the event the tamper respondent wrap is breached; and

an enclosure monitor to activate the erase circuit in the event a breach is detected.

11-14. (Canceled)

15-16. (Canceled)

17. (Currently amended) ~~The method of claim 16;~~ A method of forming a security enclosure, comprising:

providing a circuit card;

enclosing the card in a tamper respondent cloth, wherein an adhesive secures fold lines of the cloth;

holding the fold lines of the cloth to maintain adhesive contact; and

heating the enclosed card,

wherein the method further comprising holding the cloth in a clamping device to maintain the adhesive contact, and

wherein the clamping device comprises:

a base upon which a security enclosure rests;

a first stationary arm mounted on the base, which holds a first end of the security enclosure;

a second arm slidably mounted on the base; and

a traversing mechanism to bias the second arm toward a second end of the security enclosure.

18. (Currently amended) The method of claim ~~15~~ 17, further comprising heating the enclosed card at 60 °C for 1 hour.

19. (Currently amended) The method of claim ~~15~~ 17, further comprising curing the adhesive.

20. (Currently amended) The method of claim ~~15~~ 17, wherein the circuit card comprises a cryptographic processor.

21-26. (Canceled)

27. (Previously presented) A security enclosure, comprising:

an electronic assembly;

a tamper respondent wrap, such that the wrap forms fold lines at a first and second end of the assembly, said wrap enclosing the electronic assembly; and

a fixture in which the enclosed assembly is placed, wherein the fixture comprises a base upon which the assembly rests, a first stationary arm mounted on the base holding the fold lines at the first end of the assembly, a second arm slidably mounted on the base, and a traversing mechanism to bias the second arm toward the fold lines at the second end of the assembly.

28. (Previously presented) The security enclosure of claim 27, wherein the fixture comprises a clamping device.

29. (Previously presented) The security enclosure of claim 27, wherein the tamper respondent wrap comprises a flexible material having tamper respondent detection devices.

30. (Previously presented) The security enclosure of claim 27, wherein the tamper respondent wrap comprises:

at least one pierce and laser respondent layer;

a delamination respondent layer; and

an adhesive between the pierce and laser respondent layer and the delamination respondent layer.

31. (Previously presented) The security enclosure of claim 30, wherein the pierce and laser respondent layer and the delamination respondent layer comprise a plurality of ink lines on at least one side of the pierce and laser respondent layer and the delamination respondent layer.

32. (Previously presented) The security enclosure of claim 27, wherein the electronic assembly comprises a cryptographic processor.

33. (Previously presented) The security enclosure of claim 32, wherein the cryptographic processor comprises a printed circuit board, having mounted thereon:

an encryption module to carry secured sensitive information;

a memory to store a key necessary to access the information;

an erase circuit to erase the information in the encryption module in the event the tamper respondent wrap is breached; and

an enclosure monitor to activate the erase circuit in the event a breach is detected.

34. (New) The method of claim 1, wherein the second arm is a traversing clamping arm, and wherein the traversing mechanism comprises a biasing screw, a hydraulic mechanism, and an electro-mechanical sensor motor which collectively function to bias the traversing clamping arm toward or away from the first stationary arm.

35. (New) The method of claim 1, wherein the fixture comprises a clamping device for mechanically clamping the enclosed assembly, wherein said heating is performed after said placing is performed, wherein during said heating the enclosed assembly is held snugly in the clamping device by being mechanically clamped between the second arm and the first stationary arm, wherein during said heating the enclosed assembly is exposed to an ambient atmosphere and is directly exposed to heat which passes from a heating source through the ambient environment to the enclosed assembly, and wherein after said heating is performed the method further comprises removing the enclosed assembly from the clamping device.

36. (New) The method of claim 7, wherein said heating initially causes the adhesive to soften which results in the pierce and laser respondent layer sliding past the delamination respondent

layer in fold areas of the tamper respondent wrap such that the tamper respondent wrap bends more easily, wherein said heating causes the adhesive to cross-link or cure due to thermal aging which results in the adhesive becoming more solidified, and wherein after said heating is performed the adhesive continues to harden in said fold areas while the tamper respondent wrap is being cooled which results in the tamper respondent wrap having an improved fold retention.

37. (New) The method of claim 17, wherein the second arm is a traversing clamping arm, and wherein the traversing mechanism comprises a biasing screw, a hydraulic mechanism, and an electro-mechanical sensor motor which collectively function to bias the traversing clamping arm toward or away from the first stationary arm.

38. (New) The method of claim 17, wherein during said heating the enclosed card is held snugly in the clamping device by being mechanically clamped between the second arm and the first stationary arm, wherein during said heating the enclosed card is exposed to an ambient atmosphere and is directly exposed to heat which passes from a heating source through the ambient environment to the enclosed card, and wherein after said heating is performed the method further comprises removing the enclosed card from the clamping device.

39. (New) The method of claim 17, wherein the tamper respondent cloth comprises at least one pierce and laser respondent layer, a delamination respondent layer, and an adhesive between the pierce and laser respondent layer and the delamination respondent layer, wherein said heating initially causes the adhesive to soften which results in the pierce and laser respondent layer

sliding past the delamination respondent layer in fold areas of the tamper respondent cloth such that the tamper respondent cloth bends more easily, wherein said heating causes the adhesive to cross-link or cure due to thermal aging which results in the adhesive becoming more solidified, and wherein after said heating is performed the adhesive continues to harden in said fold areas while the tamper respondent cloth is being cooled which results in the tamper respondent cloth having an improved fold retention.

40. (New) The security enclosure of claim 27, wherein the second arm is a traversing clamping arm, and wherein the traversing mechanism comprises a biasing screw, a hydraulic mechanism, and an electro-mechanical sensor motor which collectively function to bias the traversing clamping arm toward or away from the first stationary arm.

41. (New) The security enclosure of claim 28, wherein the enclosed electronic assembly is being held snugly in the clamping device by being mechanically clamped between the second arm and the first stationary arm, and wherein the enclosed electronic assembly is being exposed to an ambient atmosphere and is directly exposed to heat that has passed through the ambient environment.

42. The security enclosure of claim 27, wherein the clamping device comprises a plurality of legs attached to the base, and wherein the base is disposed between the plurality of legs and both the first stationary arm and the second arm.